

IN THE SPECIFICATION:

Page 3, first paragraphs:

al In the manufacture of semiconductor devices, objectionable particulates includes bacteria, which often are of the same order of magnitude in size as conductor spacings in such devices.

IN THE CLAIMS:

Claim 1 (currently amended)

Q1. A method of packaging a PVA sponge for use in scrubbing semiconductor wafers, said method comprising:

- A2
- (a) placing said sponge in a container;
 - (b) said sponge containing [placing in said container] a quantity of de-ionized water with around 0.05% to 1% by volume of hydrogen peroxide; and
 - (c) sealing said container.

Claim 2 (original)

2. A method as in Claim 1 in which said container is a flexible plastic bag made of a material resistant to deterioration due to contact with hydrogen peroxide, preferably polyethylene.

Claim 3 (currently amended)

3. A method as in Claim 1 in which said quantity of de-ionized water with hydrogen peroxide is between an amount

sufficient to wet said sponge and an [is at least equal to the]
amount necessary to saturate said sponge.

Claim 4 (currently amended)

4. A method as in Claim 1 in which the volume of
hydrogen peroxide [said amount] is around 0.1%.

Claim 5 (currently amended)

*all
and*
A method of packaging a cleaning article, said method
comprising placing said cleaning article in a container, said
cleaning article containing [placing in said container] a
quantity of de-ionized water, said water containing hydrogen
peroxide in an amount effective to kill and retard the growth of
bacteria in said cleaning article [sponge] but less than an
amount sufficient to develop significant quantities of metallic
ions in said container, and sealing said container, in which
said amount of hydrogen peroxide is about 0.05 to 1% by volume.

Claim 6 (original)

A method as in Claim 5 in which said cleaning article
is a PVA sponge brush.

Claim 7 (original)

A method as in Claim 5 in which said cleaning article
is a clean room wiper.

Claim 8 (withdrawn)

Claim 9 (currently amended)

A2
Amended

A packaged cleaning article for use in clean rooms, said cleaning article having particulate, metal ion and anionic counts at or below the values specified for a clean room, said package comprising a sealed container, said cleaning article being positioned in said container, and containing a quantity of de-ionized water[in said container], said de-ionized water [said water] containing hydrogen peroxide in a concentration [an amount] effective to kill and retard the growth of bacteria in said cleaning article, said amount being low enough to substantially ensure decomposition of said hydrogen peroxide in a relatively short period of time after the container is sealed [sponge but less than an amount sufficient to develop significant quantities of metallic ions in said container].

Claim 10 (withdrawn)

Claim 11 (currently amended)

11. A cleaning article as in Claim 9 in which said [quantity] concentration of hydrogen peroxide in said de-ionized water with hydrogen peroxide is between approximately 0.05% and 1% [an amount sufficient to wet said cleaning article and an amount sufficient to more than saturate said cleaning article].

Claim 12 (currently amended)

12. A cleaning article as in Claim 9 in which said cleaning article is a PVA sponge for scrubbing semiconductor